CALL FOR PAPERS

INTERCON 2023

November 02-04, Lima - Perú

The XXX International Conference on Electronics, Electrical Engineering and Computing - INTERCON 2023 is a prestigious international technical conference organized by the IEEE Peru Section to bring together technological applications, knowledge, and understanding. INTERCON 2023 is the XXX version of the conference and is themed around the IEEE Future Directions platforms. The venue of the 2023 edition of INTERCON is UPC (Universidad de Ciencias Aplicadas) and its IEEE UPC Student Branch. We invite you to submit technical papers for oral presentations. INTERCON 2023 aims to continue the legacy of its predecessors by serving as a great platform for researchers to discuss and explore advanced technologies that can advance humanity.

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Topics (but not limited to):

- T1. Artificial Intelligence and Machine learning
- T2. Communications and Networking
- T3. Power, Energy, and Power Electronics
- T4. Biomedical Engineering & Healthcare Technologies
- T5. Robotics, Control, Instrumentation, and Automation
- T6. Multimedia Signal Processing and Analytics
- T7. Devices, Circuits, and Materials
- T8. RF Circuits, Systems, and Antennas
- T9. Data Science and Computing Technologies
- T10. Education in Engineering and Technology

Submission:

The conference invites research papers of varying length from 6 to 8 pages (including abstract and references) and written in English. The format of the papers is based on IEEE conference template, which can be downloaded from:

https://www.ieee.org/conferences/publishing/templates.html

For all accepted papers, the authors will be asked to sign a copyright transfer on the contents of their paper(s). The accepted papers will be indexed and published on the IEEE Xplore digital library

All papers, only in PDF file, must be submitted electronically through the EasyChair:

https://easychair.org/conferences/?conf=2023ieeeintercon

Important Dates - Regular Track

Paper submission deadline:	July 31, 2023
Notification:	September 15, 2023
Camera-ready:	October 05, 2023
Author registration deadline:	October 12, 2023